

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
FAN XIE	12/27/2023
<b>RECEIVING PARTY DATA</b>	
<b>Company Name:</b>	UNITED IMAGING RESEARCH INSTITUTE OF INNOVATIVE MEDICAL EQUIPMENT
<b>Street Address:</b>	8-13F, Building B, Shenjiu International Science and Technology Park
<b>Internal Address:</b>	No. 3, Binglang Road, Bonded Area, Futian District
<b>City:</b>	Shenzhen
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	518045
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17819306
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>ATTORNEY DOCKET NUMBER:</b>	20618-1126US00
<b>NAME OF SUBMITTER:</b>	qiantong xu
<b>SIGNATURE:</b>	qiantong xu
<b>DATE SIGNED:</b>	08/07/2024
<b>Total Attachments: 5</b>	
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source=2023-12-27-signed assignment-20618-1126US00#page4.tiff	



## ASSIGNMENT

WHEREAS I/WE, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:

### SYSTEMS AND METHODS FOR DATA PROCESSING

for which a U.S. application was filed on August 11, 2022 (U.S. Application No. 17/819,306), claiming priority to Chinese Patent Application No. 202110918085.1 filed on August 11, 2021; and

WHEREAS, UNITED IMAGING RESEARCH INSTITUTE OF INNOVATIVE MEDICAL EQUIPMENT, a Chinese company whose address is 8-13F, Building B, Shenjiu International Science and Technology Park, No. 3, Binglang Road, Bonded Area, Futian District, Shenzhen, Guangdong, 518045, P.R. China (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to all applications for patents on this invention in all countries throughout the world, including any PCT International Application and all national stage applications based thereon that may be filed, any other applications for patents filed anywhere in the world that claim this invention, and all divisions and continuations of any such application, all patents issued upon such applications in all countries throughout the world, and all reissues thereof, and all rights to claim priority in any country on the basis of the above applications, and all extensions, renewals, and reissues thereof;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention, any PCT International Application and all national stage applications based thereon that may be filed, any other applications for patents filed anywhere in the world that claim this invention, and all divisions and continuations of any such application, and all patents which may be granted thereon, and all reissues thereof, and all rights to claim priority in any country on the basis of the above applications, and all extensions, renewals, and reissues thereof; and I/We hereby authorize and request any official of any country whose duty is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in Assignee, its successors or assigns, execute all national phase, national, divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in any country in the world, it being understood that any expense incident to the execution of such papers shall be borne by Assignee, its successors and assigns.

AND, I/WE authorize and request a patent practitioner of record in this application, to insert the filing date, country of filing, and application number of the above-referenced application(s) when known.

IN TESTIMONY WHEREOF, I/We have hereunto set my/our hands.

Assignor

Signature:



Print Name:

XIE, Fan

Execution Date:

2022.12.27

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Assignee

UNITED IMAGING RESEARCH INSTITUTE  
OF INNOVATIVE MEDICAL EQUIPMENT

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Title: Vice President  
Execution Date: 2023-12-27

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